Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1113	ARITA-KIYOSHI.in. IWAI-TETSUHIRO.in. NAKAGAWA-AKIRA.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 12:05
S2	1	S1 and (blocking with ring) and (cover with ceramic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 12:22
S3	1	S1 and (blocking with ring)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 12:20
S4	0	"matsushita-electric.as"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 12:21
S5	559065	matsushita adj electric.as.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 12:22
S6	1	S5 and (blocking with ring) and (cover with ceramic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 12:23
S7	30	S5 and (blocking with ring)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 12:32

[T		1	
S8	4	("20030037882" "6583979").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 13:16
S9	6	"2001033369".pn. "2002140148". pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 13:17
S10	. 3	"2001077184".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 13:21
S11	0	"2001033369".pn. "2005018169". pn. "2002140148".pn.	US-PGPUB	OR	ON	2007/07/27 13:22
S12	1	"2001326270".pn.	JPO	OR	ON	2007/07/27 13:30
S13	0	"2002140148 A1"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 13:31
S14	12	"1215716"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/07/27 13:32
S15	1	"EP 1215716"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/27 13:34

10	10 ("448 "5055 "534 "5625 "5909	0140148".pn. 0284" "4520421" 964" "5099571" "5191506" 15999" "5572398"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB US-PGPUB;	OR OR	ON	2007/07/27 13:34
·	"5055 "534 "5625 "5909	964" "5099571" "5191506" }5999" "5572398"	1	OR		
32	URPN	526" "5886863" 354").PN. OR ("6583979").	USPAT; USOCR		ON	2007/07/27 17:41
		4918" "5055964" 571").PN. OR ("5572398").	US-PGPUB; USPAT; USOCR	OR [.]	ON	2007/07/27 18:19
48565	48565 (118/ 118/7 118/7 118/7 or 156 ccls. o 156/3 or 15 156/3 ccls. o or 13 or 13 ccls. o 137/5 05-59 (141/ or 14 141/3 or (26 261/1 or 26 261/9 ccls. o	715.ccls. or 118/724.ccls. or 25.ccls. or 118/728.ccls. or 10.ccls. or 118/723e.ccls. or 10.ccls. or 118/723e.ccls. or 23er.ccls. or 156/345.26.ccls. or 156/345.29.ccls. or 156/345.33. or 156/345.34.ccls. or 156/345.36.ccls. or 156/345.36.ccls. or 156/345.36.ccls. or 156/345.43-345.47.ccls or 45.51.ccls.) or (137/262-264. or 137/454.2 or 137/560.ccls. or 137/561a.ccls. or 137/591. or 137/594-596.ccls. or 137/590. or 137/594-596.ccls. or 199.01.ccls. or 137/602.ccls.) or 285-286.ccls. or 141/37.ccls. 1/44-47.ccls. or 141/367.ccls. or 161-302.ccls. or 141/367.ccls. or 261/131.ccls. or 46-147.ccls. or 261/131.ccls. or 46-147.ccls. or 261/131.ccls. or 261/42.ccls. or 261/42.ccls. or 1496.ccls. or 261/100-102. or 261/105.ccls. or 261/100-102. or 261/105.ccls. or 261/113.ccls. or 08-109.ccls. or 261/113.ccls. 1/114.1.ccls.) 156/345.52,345.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:57
1584	pedes platfo	stal platen stage holder rm mounting) with (cover or	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT;	OR	ON	2007/07/28 15:23
	•	261/9 ccls. c 261/1 or 26: 53.ccl 1584 S19 a pedes platfo	261/94-96.ccls. or 261/100-102. ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.) 156/345.52,345. 53.ccls.	261/94-96.ccls. or 261/100-102. ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.) 156/345.52,345. 53.ccls. S19 and ((susceptor support chuck pedestal platen stage holder platform mounting) with (cover or "insulating film")) US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO;	261/94-96.ccls. or 261/100-102. ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.) 156/345.52,345. 53.ccls. S19 and ((susceptor support chuck pedestal platen stage holder platform mounting) with (cover or "insulating film")) US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO;	261/94-96.ccls. or 261/100-102. ccls. or 261/105.ccls. or 261/108-109.ccls. or 261/113.ccls. or 261/114.1.ccls.) 156/345.52,345. 53.ccls. S19 and ((susceptor support chuck pedestal platen stage holder platform mounting) with (cover or "insulating film")) WS-PGPUB; US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO;

S21	20725	S19 and (@rlad<="20030723" or @ad<="20030723")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:22
S22	1175	S21 and ((susceptor support chuck pedestal platen stage holder platform mounting) with (cover or "insulating film"))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 18:21
S23	52	S22 and (cover with detach\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:16
S24	87	S22 and (cover with protect)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/28 16:16
S25	84	S24 not S23	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON ·	2007/07/28 16:16
S26	19	("3179213" "4078812" "4167351" "4668373" "5066381" "5074456" "5161908" "5178681" "5238499" "5257872" "5269894" "5494523").PN. OR ("5589003").URPN.	US-PGPUB; USPAT; USOCR	OR ·	ON	2007/07/28 18:04
S27	223	S21 and (shield\$2 with (substrate or wafer) with (support or holder))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 16:10

S28	160	(plasma and (chamber with (substrate or wafer))) and ((small\$2 adj (substrate or wafer)) same (larg\$2 adj (substrate or wafer)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 11:00
S29	263	((chamber with (substrate or wafer))) and ((small\$2 adj (substrate or wafer)) same (larg\$2 adj (substrate or wafer)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 17:26
S30	103	S29 not S28	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/07/29 17:41
S31	1	S30 and ((accommodat\$3 or adapt\$3) near3 (small and large))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 17:29
S32	16	("3467242" "4261464" "4308953" "4446966" "4574950" "4602715" "5653565" "5706946" "5711427" "5755332").PN. OR ("6095335"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/29 17:35
S33	102	S30 not (S31 S32)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 17:41
S34	. 13	("4261762" "4457359" "4512391" "4542298" "4680061" "4705951" "4743570" "4909314" "4949783" "5001423" "5583737").PN. OR ("6183523"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/29 18:14

635		IIC022720II	LIC D'CDUB	00	ON	2007/07/20 40:46
S35	2	"6822730".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/29 18:16
S36	6	("20030211813" "5441911" "5820329" "6164633" "6258228").PN. OR ("6822730"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/29 18:16
S37	14	("4131267" "4448404" "5191218" "5324012" "5564682" "6032997").PN. OR ("6164633"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/29 18:18
S38	4	(plasma and (chamber with (substrate or wafer))) and ((susceptor support chuck mount\$3 holder stage platform pesdestal platen) with ((inner and outer) adj area))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 11:10
S39	. 1	(plasma and (chamber with (substrate or wafer))) and ((substrate adj support) with ((inner and outer) adj area))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 11:13
S40	1	((chamber with (substrate or wafer))) and ((substrate adj support) with ((inner and outer) adj area))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 11:13
S41	10	((chamber with (substrate or wafer))) and ((substrate adj support) with (insulating adj film))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 11:19
S42	316	((chamber with (substrate or wafer))) and ((support susceptor pedestal mounting chuck) with (insulating adj film))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 11:34

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S43	646	((chamber with (substrate or wafer))) and ((support susceptor pedestal mounting chuck) with (divided))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 14:57
S44	17	((chamber with (substrate or wafer))) and ((support susceptor pedestal mounting chuck) with (divided adj (area section portion)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 11:21
S45	129	S42 and (insulat\$3 with (ring separat\$3 concentric area divide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 11:36
S46	1100	((chamber with (substrate or wafer))) and ((support susceptor pedestal mounting chuck) with (suction))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 14:58
S47	524	((chamber with (substrate or wafer))) and ((support susceptor pedestal mounting chuck) near3 (suction))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 14:58
S48	331	S47 and (suction near3 (wafer substrate))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 15:20
S49	20	("20020021959" "20030038112" "2 0030053075" "20030056899" "5589 928" "5796486" "6077387" "616463 3" "6511895" "6592673").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 15:20

S50	2881	118/728.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 16:45
S51	329	S50 and ((small and large) with (substrate wafer))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 16:48
S52	319	S51 not (S38 S39 S40 S41 S42 S44 S45 S48 S49)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 16:47
S53	569	S50 and ((small\$2 and large\$2) with (substrate wafer))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 16:48
S54	54	S50 and ((small\$2 and large\$2) adj (substrate wafer))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 17:48
S55	33	(quantum adj dot) and substrate and atomizer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 18:03
S56		"4692836".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/30 19:10

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S57	54	("4384918" "4520421").PN. OR ("4692836").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/31 22:58
S58	144	("3634740" "3916270" "4184188" "4282267" "4292153" "4313783" "4324611").PN. OR ("4384918").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/31 12:49
S59	784	361/234.ccls.	US-PGPUB; USPAT; USOCR	OR	ON .	2007/07/31 13:01
S60	607	S59 and (@rlad<="20030723" or @ad<="20030723")	US-PGPUB; USPAT; USOCR	OR	ON .	2007/07/31 13:02
S61	13	S60 and (plasma and suction)	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/31 13:02
S62	5	("6556414").URPN.	USPAT	OR	ON	2007/07/31 13:15
S63	54	("4384918" "4520421").PN. OR ("4692836").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/07/31 22:59
S64	9	S63 and (insulat\$3 near3 ceramic)	US-PGPUB; USPAT; USOCR	OR '	ON .	2007/08/01 11:21
S65	14	("electrostatic adj chuck" "esc") and (vacuum same (suction near3 hole))	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 11:30
S66	4023	(chuck susceptor holder support) same ((vacuum or suction) near3 hole)	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 11:32
S67	424	(chuck susceptor holder support) with (substrate or wafer) with ((vacuum or suction) adj hole)	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 11:46
S68	125	S67 and plasma	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 15:19
S69	15	S67 and (cover\$3 near3 holes)	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 14:49
S70	784	361/234.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 16:08
S71	12	S66 and S70	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 14:50
S72	123	S68 not (S69 S71)	US-PGPUB; USPAT; USOCR	OR .	ON	2007/08/01 15:20

S73	15	S70 and ("dummy wafer")	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 16:08
S74		("4384918" "5055964" "5151845" "5548470" "5572398" "5612850" "5671119" "5675471" "5677824" "5699223" "5781400" "5793192" "5798904" "5946184").PN. OR ("6243251").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 16:54
S75		("dummy wafer" with cover with hole) and (plasma with chamber with substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:58
S76	. 1	("dummy wafer" with cover with hole) and (chamber with substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/01 16:58
S77	0	("2006/0175772").URPN.	USPAT	OR	ON	2007/08/01 17:34
S78	0	(plasma same (chamber with (substrate or wafer))) and (((vacuum or suction) adj holes) with cover)	USPAT	OR	ON	2007/08/01 17:55
S79	6	((chamber with (substrate or wafer))) and (((vacuum or suction) adj holes) with cover)	USPAT	OR	ON	2007/08/01 17:55
S80	2	"6815646".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/08/01 20:31
S81	14	("4131267" "4448404" "5191218" "5324012" "5564682" "6032997").PN. OR ("6164633"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 20:53
S82	11	("4158171" "4796562" "4846452" "4849916" "5923408" "6032997" "6073681" "6164633" "6196532" "6257564").PN. OR ("6538733"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/01 20:55

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S83	2882	118/728.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:21
S84	2632	S83 and (@rlad<="20030723" or @ad<="20030723")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:22
S85	928	S84 and (ring)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/02 18:23
S86	238	S85 and (ring with (cover\$3 or protect\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 12:55
S87	2882	118/728.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 12:55
S88	2632	S87 and (@rlad<="20030723" or @ad<="20030723")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 12:55
S89	928	S88 and (ring)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 12:55

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S90	5	S89 and (ring near3 resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 12:55
S91	6	(US-5625526-\$ or US-5589003-\$ or US-6164633-\$ or US-6815646-\$ or US-5463526-\$). did.	USPAT	OR	ON.	2007/08/03 13:00
S92	2	S91 and resin	USPAT	OR	ON	2007/08/03 13:11
S93	858	156/345.14,345.23,345.51.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 15:24
S94	102	S93 and (ring near3 (cover\$3 or protect\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 15:26
S95	13	S93 and (ring near3 material near2 (substrate wafer))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/03 15:26